

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ADG/20/11961	
1.3 Title of PCI	TDA770xx (HF01): KYEC Site Relocation in Taiwan	
1.4 Product Category	see list	
1.5 Issue date	2020-02-20	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo MOIOLI
2.1.2 Marketing Manager	Guido BRASCA
2.1.3 Quality Manager	Marcello Donato MENCHISE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Electrical wafer sort (SOP 2617)	Subcon KYEC (Chunan-Taiwan)

4. Description of change

	Old	New
4.1 Description	Current location: Hsinchu (Taiwan)	New location: Chunan (Taiwan)
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Service and Capacity increase
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Date Code
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7. Timing / schedule

7.1 Date of qualification results	2020-01-17
7.2 Intended start of delivery	2020-02-28
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	11961 Validation.docx		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2020-02-20

9. Attachments (additional documentations)

11961 Public product.pdf
11961 Validation.docx
11961 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	TDA7703TR	
	TDA7705	

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Public Products List

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PCI Title : TDA770xx (HF01): KYEC Site Relocation in Taiwan

PCI Reference : ADG/20/11961

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

TDA7705TR	TDA7705	
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PRODUCT/PROCESS CHANGE INFORMATION

SUBJECT TDA770xx (HF01): KYEC Site Relocation in Taiwan

IMPACTED PRODUCTS	ST silicon line HF01, part of ST silicon line MV60 (dual chip), used inside following products: - TDA7703 - TDA7703TR - TDA7703R - TDA7703RTR - TDA7705 - TDA7705TR
MANUFACTURING STEP	Electrical Wafer Sorting (EWS) – Wafer Probing
INVOLVED PLANT	Subcontractor KYEC (Taiwan)
CHANGE REASON	Service – Capacity Increase
CHANGE DESCRIPTION	Relocation of existing EWS equipment in a new existing building in Taiwan, from current Hsinchu site to Chunan site:  Relocation is following a “one by one approach”: each complete test cell (tester and relevant prober) is transferred to new site and revalidated. Production team in Hsinchu is moving to Chunan: same Company, geographical area, physical equipment and personnel. Transferred device is submitted to revalidation procedure in the new site, before production restart.
TRACEABILITY	Internal Traceability (date code)

VALIDATION	Standard correlation procedure: product wafers probed in the original location, re-tested in the new one, and relevant results compared
CURRENT PRODUCTS	Production in current location (Hsinchu) stops and the new one (Chunan) remains the only active
REPORTS	See enclosed validation report 11961 Validation.docx